

# CD4048B Types

## CMOS Multifunction Expandable 8-Input Gate

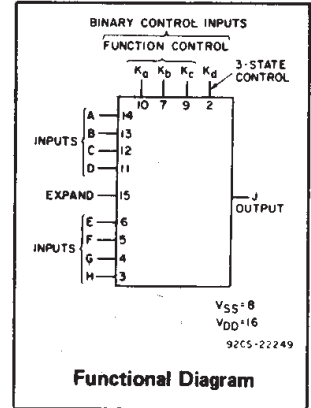
High-Voltage Types (20-Volt Rating)

■ CD4048B is an 8-input gate having four control inputs. Three binary control inputs — Ka, Kb, and Kc — provide the implementation of eight different logic functions. These functions are OR, NOR, AND, NAND, OR/AND, OR/NAND, AND/OR and AND/NOR.

A fourth control input, Kd, provides the user with a 3-state output. When control input Kd is high, the output is either a logic 1 or a logic 0 depending on the inner states. When control input Kd is low, the output is an open circuit. This feature enables the user to connect this device to a common bus line.

In addition to the eight input lines, an EXPAND input is provided that permits the user to increase the number of inputs into a CD4048B (see Fig. 2). For example, two CD4048Bs can be cascaded to provide a 16-input multifunction gate. When the EXPAND input is not used, it should be connected to V<sub>SS</sub>.

The CD4048B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).



**MAXIMUM RATINGS, Absolute-Maximum Values:**

DC SUPPLY-VOLTAGE RANGE, (V <sub>DD</sub> )		-0.5V to +20V
Voltages referenced to V <sub>SS</sub> Terminal		
INPUT VOLTAGE RANGE, ALL INPUTS		-0.5V to V <sub>DD</sub> +0.5V
DC INPUT CURRENT, ANY ONE INPUT		±10mA
POWER DISSIPATION PER PACKAGE (P <sub>D</sub> ):		
For T <sub>A</sub> = -55°C to +100°C		500mW
For T <sub>A</sub> = +100°C to +125°C		Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR		
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)		100mW
OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )		-55°C to +125°C
STORAGE TEMPERATURE RANGE (T <sub>stg</sub> )		-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):		
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max		+265°C

**Features:**

- Three-state output
- Many logic functions available in one package
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V (full package-temperature range), 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) = 1 V at V<sub>DD</sub>=5 V, 2 V at V<sub>DD</sub> = 10 V, 2.5 V at V<sub>DD</sub>=15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, 'Standard Specifications for Description of 'B' Series CMOS Devices'

**Applications:**

- Selection of up to 8 logic functions
- Digital control of logic
- General-purpose gating logic
  - Decoding
  - Encoding

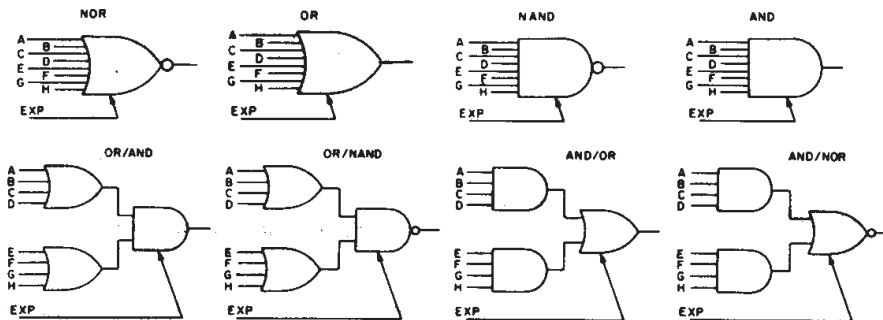
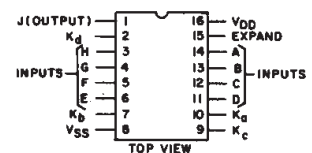


Fig. 1 - Basic logic configurations.

**RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T <sub>A</sub> = Full Package Temperature Range)	3	18	V



TERMINAL ASSIGNMENT

3  
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# CD4048B Types

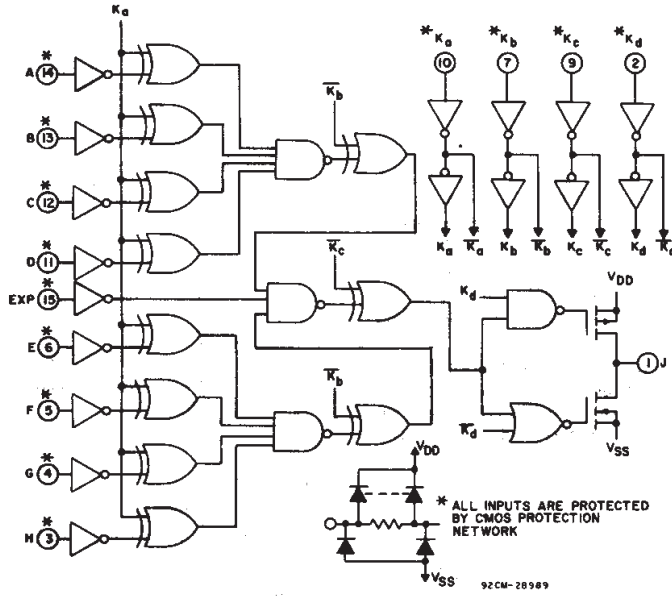


Fig. 2 - Logic diagram.

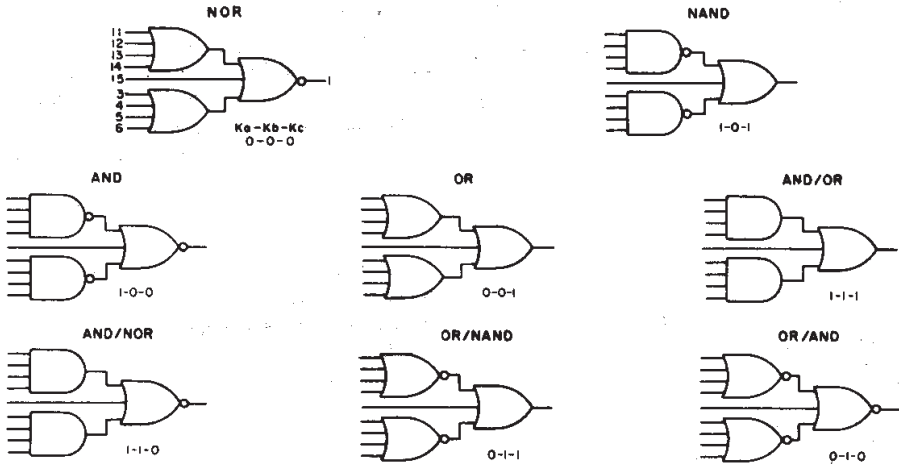


Fig. 3 - Actual-circuit logic configurations.

## APPLICATIONS OF EXPAND INPUT

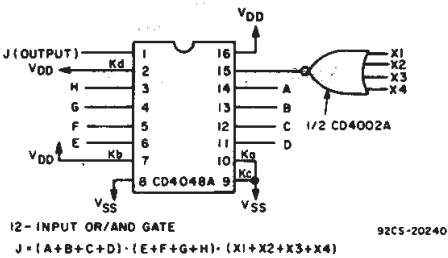


Fig. 4 - 12-input OR/AND gate.

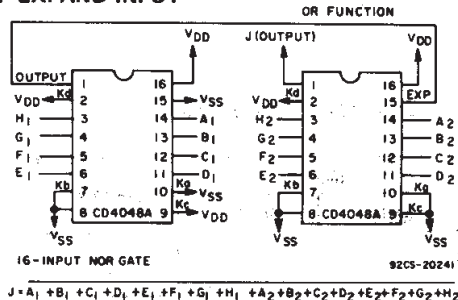


Fig. 5 - 16-input NOR gate.

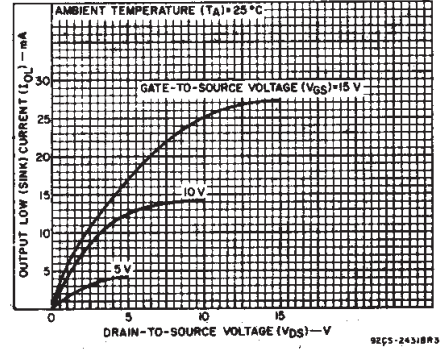


Fig. 6 - Typical output low (sink) current characteristics.

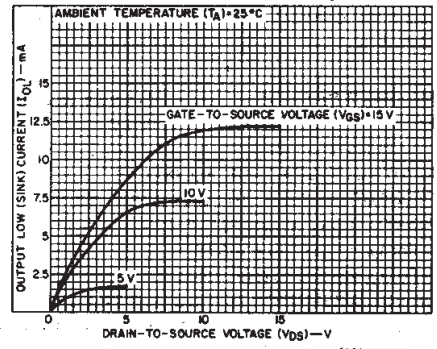


Fig. 7 - Minimum output low (sink) current characteristics.

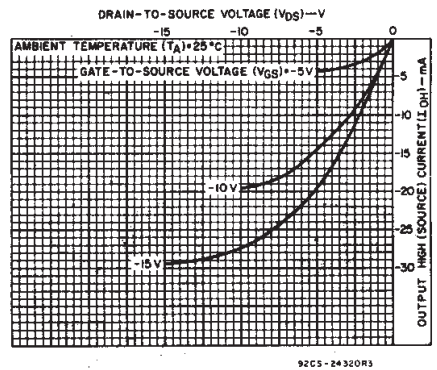


Fig. 8 - Typical output high (source) current characteristics.

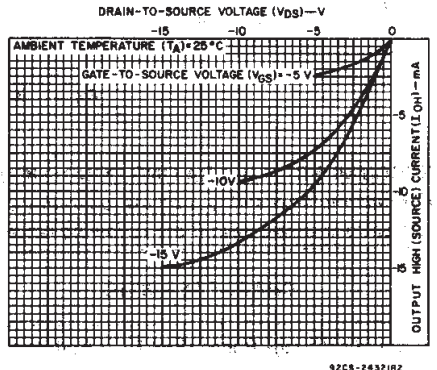


Fig. 9 - Minimum output high (source) current characteristics.

# CD4048B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	+25							
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	-	0,5	5	0.25	0.25	7.5	7.5	-	0.01	0.25	μA
	-	0,10	10	0.5	0.5	15	15	-	0.01	0.5	
	-	0,15	15	1	1	30	30	-	0.01	1	
	-	0,20	20	5	5	150	150	-	0.02	5	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	-	0,5	5	0.05				-	0	0.05	V
	-	0,10	10	0.05				-	0	0.05	
	-	0,15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	-	0,5	5	4.95				4.95	5	-	V
	-	0,10	10	9.95				9.95	10	-	
	-	0,15	15	14.95				14.95	15	-	
Input Low Voltage, V <sub>IL</sub> Max.	0.5,4.5	-	5	1.5				-	-	1.5	V
	1,9	-	10	3				-	-	3	
	1.5,13.5	-	15	4				-	-	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5,4.5	-	5	3.5				3.5	-	-	V
	1,9	-	10	7				7	-	-	
	1.5,13.5	-	15	11				11	-	-	
Input Current I <sub>IN</sub> Max.		0,18	18	±0.1	±0.1	±1	±1	-	±10 <sup>-5</sup>	±0.1	μA
3-State Output Current, I <sub>OUT</sub>	0,18	0,18	18	±0.4	±0.4	±12	±12	-	±10 <sup>-4</sup>	±0.4	μA

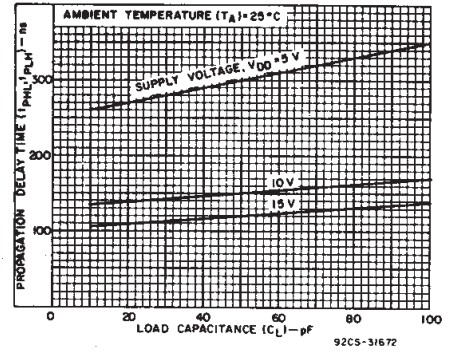


Fig. 10 - Typical propagation delay time (logic inputs to output) as a function of load capacitance.

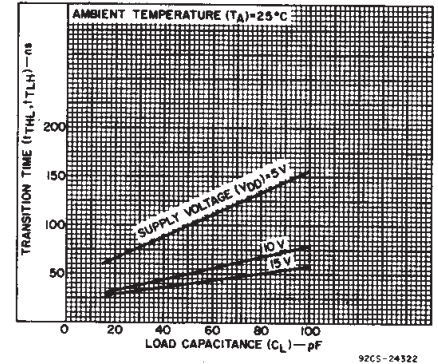


Fig. 11 - Typical transition time vs. load capacitance.

## IMPLEMENTATION OF EXPAND INPUT FOR 9 OR MORE INPUTS

OUTPUT FUNCTION	FUNCTION NEEDED AT EXPAND INPUT	OUTPUT BOOLEAN EXPRESSION
NOR	OR	$J = \overline{(A+B+C+D+E+F+G+H)} + (\text{EXP})$
OR	OR	$J = (A+B+C+D+E+F+G+H) + (\text{EXP})$
AND	NAND	$J = (ABCDEFHG) \cdot \overline{(\text{EXP})}$
NAND	NAND	$J = (ABCDEFHG) \cdot (\text{EXP})$
OR/AND	NOR	$J = (A+B+C+D) \cdot \overline{(E+F+G+H)} \cdot \overline{(\text{EXP})}$
OR/NAND	NOR	$J = (A+B+C+D) \cdot \overline{(E+F+G+H)} \cdot (\text{EXP})$
AND/NOR	AND	$J = (ABCD) + (EFGH) + (\text{EXP})$
AND/OR	AND	$J = (ABCD) + (EFGH) + (\text{EXP})$

Note: (EXP) designates the EXPAND function (i.e.,  $X_1 + X_2 + \dots + X_N$ ).

### NOTE:

Refer to FUNCTION TRUTH TABLE for connection of unused inputs.

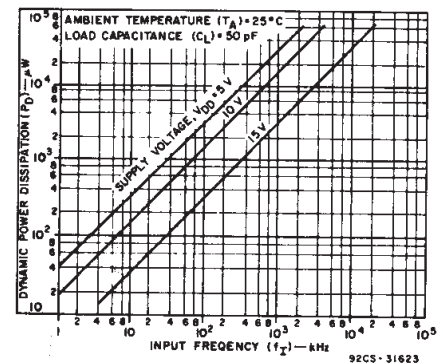


Fig. 12 - Typical power dissipation as a function of input frequency.

# CD4048B Types

DYNAMIC CHARACTERISTICS at  $T_A=25^{\circ}\text{C}$ ,  $C_L=50\text{ pF}$ , Input  $t_r, t_f=20\text{ ns}$ ,  $R_L=200\text{ k}\Omega$  unless otherwise specified

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS	
		$V_{DD}$ V	All Package Types		
			Typ.	Max.	
Propagation Delay: $t_{PHL}, t_{PLH}$ Inputs to Output and Ka to Output		5	300	600	ns
		10	150	300	
		15	120	240	
Kb to Output		5	225	450	
		10	85	170	
		15	55	110	
Kc to Output		5	140	280	
		10	50	100	
		15	40	80	
Expand Input to Output		5	190	380	
		10	90	180	
		15	65	130	
3-State Propagation Delay: Kd to Output $t_{PHZ}, t_{PLZ}$ $t_{PZH}, t_{PZL}$	$R_L=1\text{ k}\Omega$ See Fig.21	5	80	160	
		10	35	70	
		15	25	50	
Transition Time: $t_{THL}, t_{TLH}$		5	100	200	
		10	50	100	
		15	40	80	
Input Capacitance: $C_i$	Any Input		5	7	pF
3-State Output Capacitance			5	10	

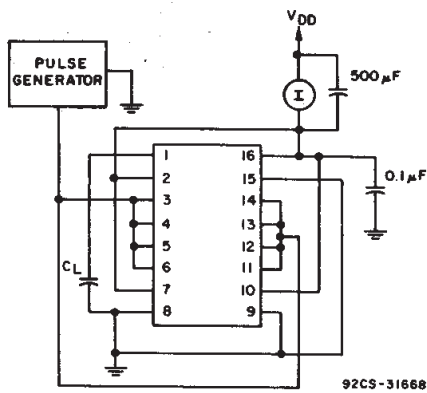


Fig. 13 - Dynamic power dissipation test circuit.

## FUNCTION TRUTH TABLE

OUTPUT FUNCTION	BOOLEAN EXPRESSION	$K_a$	$K_b$	$K_c$	UNUSED INPUT*
NOR	$J = \overline{A+B+C+D+E+F+G+H}$	0	0	0	$V_{SS}$
OR	$J = A+B+C+D+E+F+G+H$	0	0	1	$V_{SS}$
OR/AND	$J = (A+B+C+D) \cdot (E+F+G+H)$	0	1	0	$V_{SS}$
OR/NAND	$J = \overline{(A+B+C+D) \cdot (E+F+G+H)}$	0	1	1	$V_{SS}$
AND	$J = ABCDEFGH$	1	0	0	$V_{DD}$
NAND	$J = \overline{ABCDEFGH}$	1	0	1	$V_{DD}$
AND/NOR	$J = \overline{ABCD+EFGH}$	1	1	0	$V_{DD}$
AND/OR	$J = ABCD+EFGH$	1	1	1	$V_{DD}$
$K_d=1$ Normal Inverter Action					
$K_d=0$ High Impedance Output					

EXPAND Input=0

\* See Figs. 1,2,3,4, and 5.

## TEST CIRCUITS - STATIC MEASUREMENTS

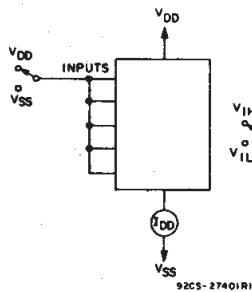


Fig. 14 - Quiescent device current test circuit.

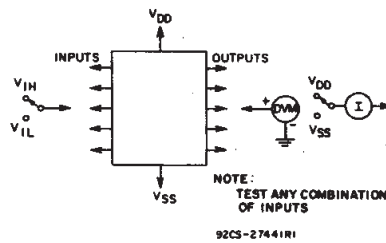


Fig. 15 - Input voltage test circuit.

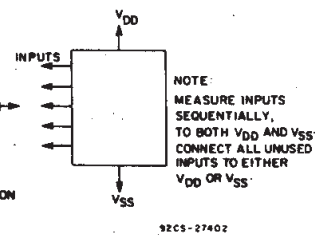


Fig. 16 - Input current test circuit.

# CD4048B Types

## TEST CIRCUITS - DYNAMIC MEASUREMENTS

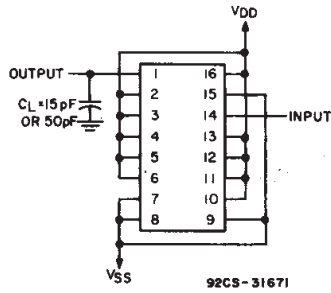


Fig. 17 - Test circuit for  $t_{PHL}$ ,  $t_{THL}$ , and  $t_{TLH}$  (AND) measurements.

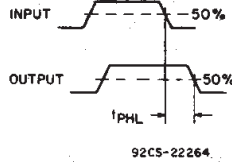


Fig. 18 - Waveforms for  $t_{PHL}$  and  $t_{PHL}$  (AND).

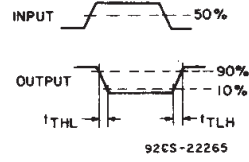


Fig. 19 - Waveforms for  $t_{THL}$  and  $t_{TLH}$  (AND).

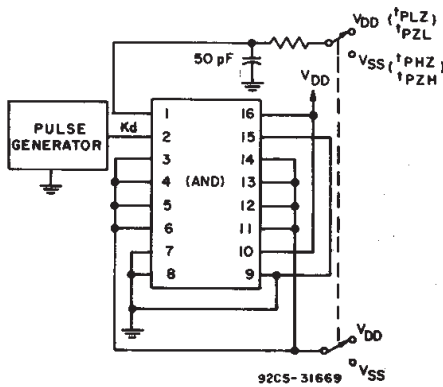


Fig. 20 - Test circuit for  $t_{PZL}$ ,  $t_{PZH}$ ,  $t_{PLZ}$ , and  $t_{PHZ}$  (AND).

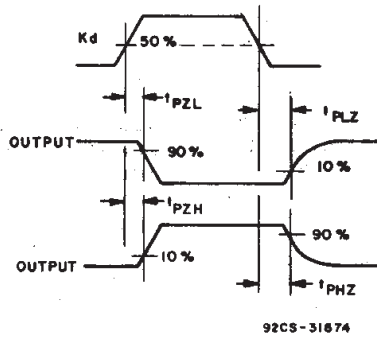
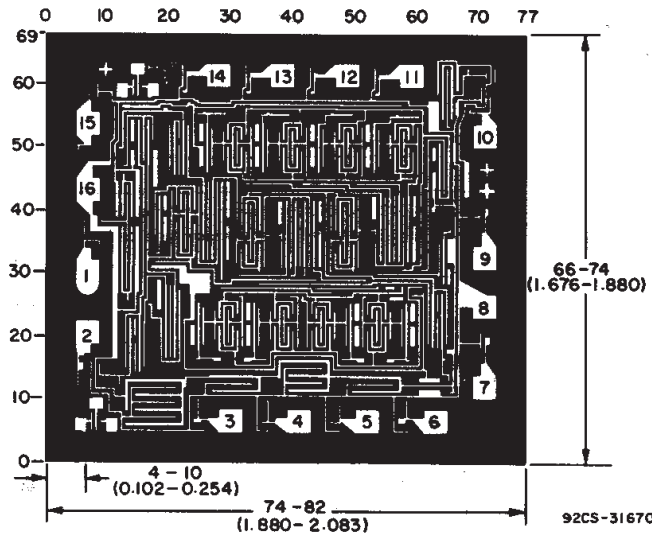


Fig. 21 - Waveforms for  $t_{PZL}$ ,  $t_{PZH}$ ,  $t_{PLZ}$ , and  $t_{PHZ}$  (AND).



Dimensions and pad layout for CD4048BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

3  
COMMERCIAL CMOS  
HIGH VOLTAGE ICs

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4048BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4048BE	<a href="#">Samples</a>
CD4048BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4048BE	<a href="#">Samples</a>
CD4048BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4048BF3A	<a href="#">Samples</a>
CD4048BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4048BM	<a href="#">Samples</a>
CD4048BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4048BM	<a href="#">Samples</a>
CD4048BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4048BM	<a href="#">Samples</a>
CD4048BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM048B	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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**OTHER QUALIFIED VERSIONS OF CD4048B, CD4048B-MIL :**

- Catalog: [CD4048B](#)
- Military: [CD4048B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4048BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4048BM96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

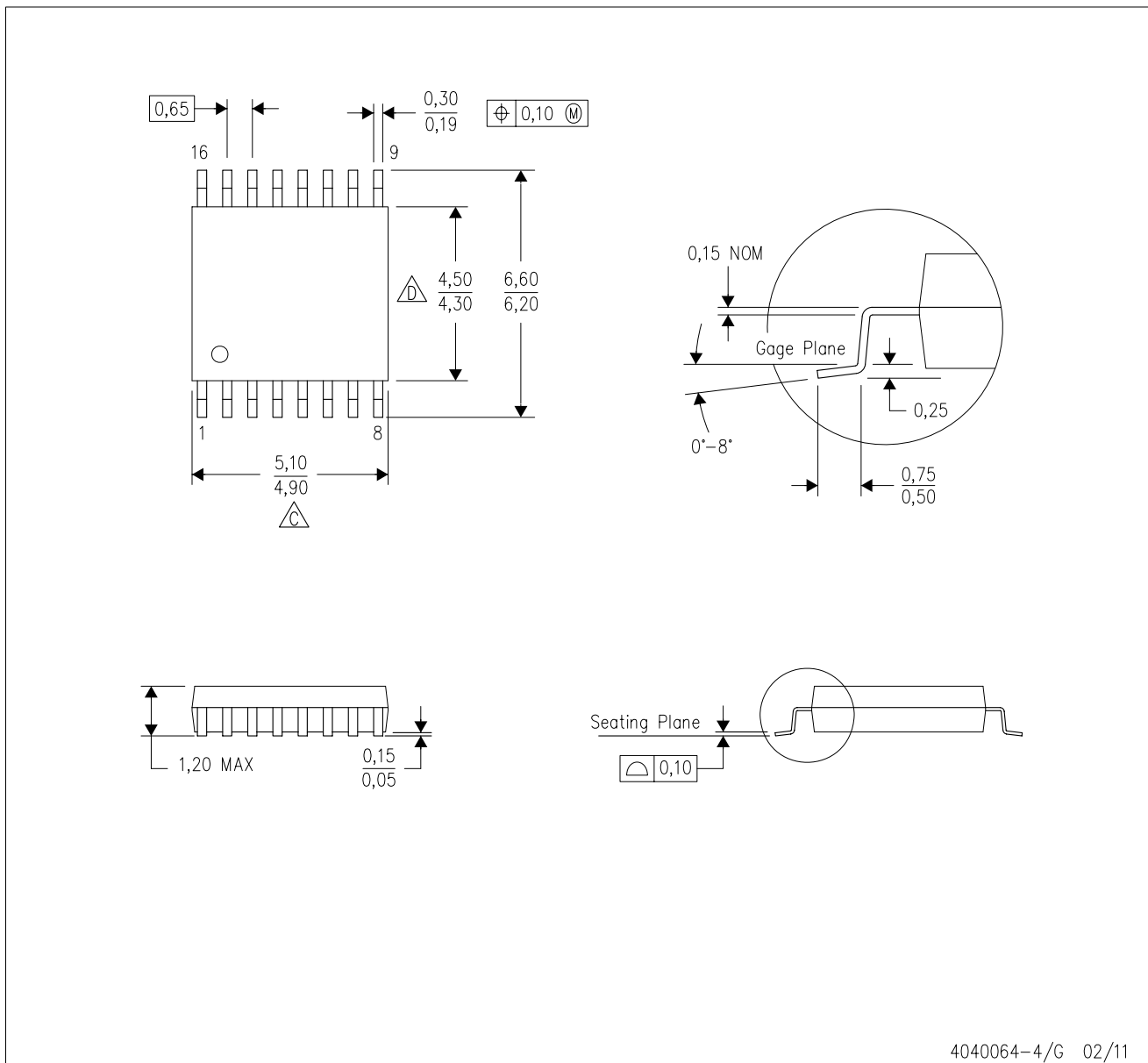
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

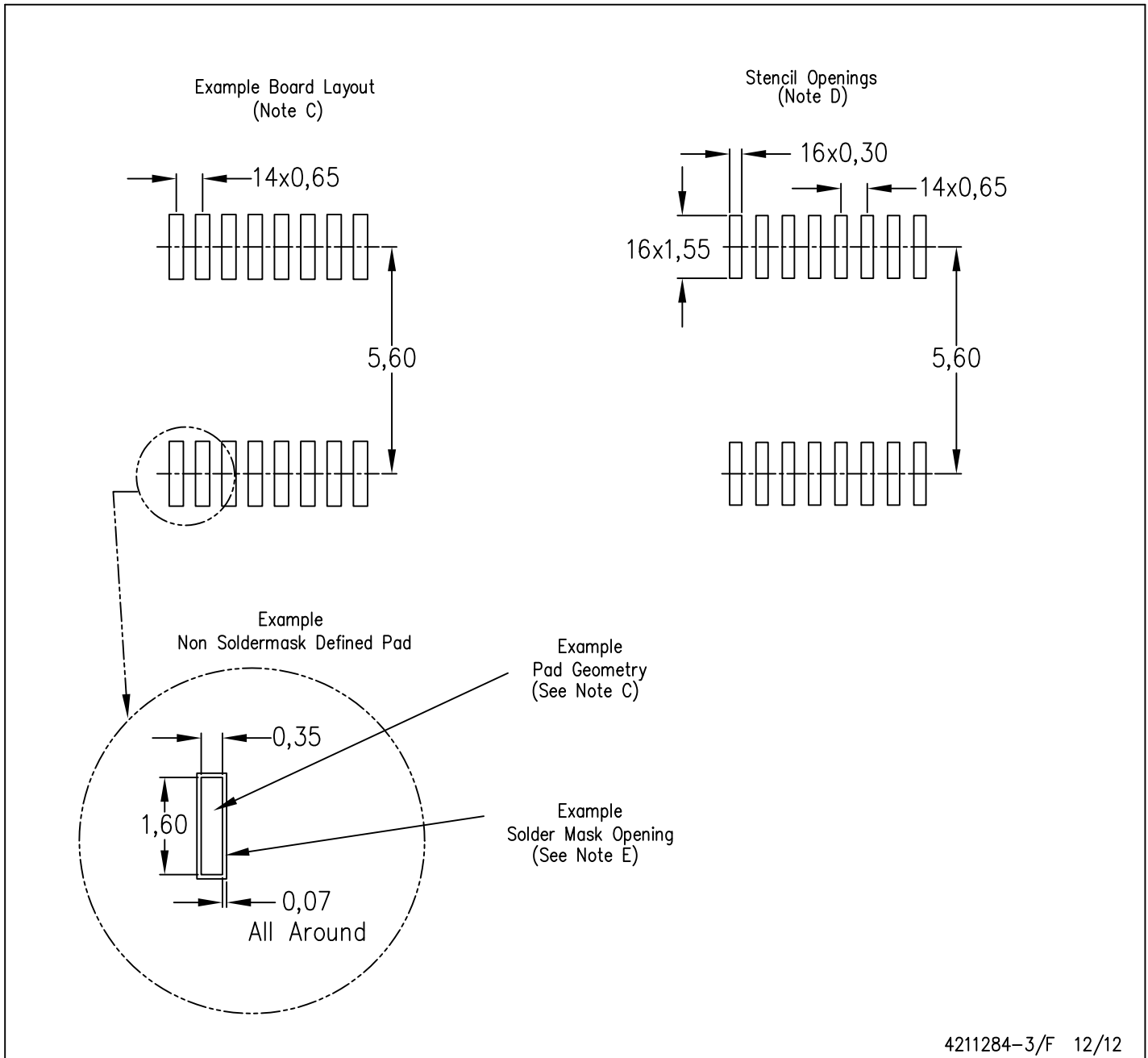


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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